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Full Material Declaration for attached parts list

Report generated: 7 September 2021, 11:01 GMT

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Declarations authorised by:
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Declaration effective from: 1 January 2021 [Approved on 7 September 2021, 10:59 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.1%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.46%
			Gold	7440-57-5	0.61%
			ALUMINIUM	7429-90-5	0.66%
			Tin elemental	7440-31-5	3.67%
			Silicon	7440-21-3	94.6%
Die attach	Others (Rubber/non-thermoplastic Elastomer)	0.2%	4,4'-Sulfonylbisbenzamine	80-08-0	2.5%
			1,4-BIS(2,3-EPOXYPROPOXY)BUTANE	2425-79-8	7.5%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	10%
			Silver	7440-22-4	80%
Encapsulation	EP (Epoxy resin)	56.8%	Carbon black	1333-86-4	1.01%
			ZINC BORATE	1332-07-6	2.02%
			Phenol, polymer with formaldehyde	9003-35-4	10.01%
			Oxirane, (chloromethyl)-, homopolymer	24969-06-0	14.99%
			Silica	7631-86-9	71.97%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.07%	Copper	7440-50-8	100%
Leadfinish	Tin plating	0.8%	Tin	7440-31-5	100%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Leadframe	Copper (e.g. copper amounts in cable harnesses)	42.03%	Elemental nickel REACH Article 67 Exemption	7440-02-0	1.1%
			Tin elemental	7440-31-5	1.7%
			Copper	7440-50-8	97.2%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-89	SOT-89	0.0497	g